

HYBRID REWORK.

Further information
on our complete rework
product range is available
on page 56 and
at rework.ersa.com



GLOBAL. AHEAD. SUSTAINABLE.

HR 200

Rework out of the Box! Rework can be that simple today.

Easy parameter setup:

		Top Heat				Parameters
		smooth		intensive		
Time*		>180 s	180-120 s	120-90 s	90-60 s	
Power level		1	2	3	4	
Bottom Heat	smooth	1	ultra light weight	sensitive bottom side		intensive top
	intensive	2	sensitive top side	typical SMT-application		
		3	intensive bottom		heavy duty caution	
	4					
*Expectable soldering time, depending on application an preheating with bottom heater.						



Order information:

Order no.	Description
OHR200	HR 200 hybrid rework system with foot switch, positioning laser and PCB holder
1HR2000000A67	HR 200, 115 V version
OHR200-HP	HR 200 hybrid rework system with foot switch, positioning laser, PCB holder and heating plate
1HR200-HP0A67	HR 200 with heating plate, 115 V version

Technical highlights:

- 400 W hybrid high-power heating element
- Optional 800 W IR heating plate
- Simple power selection in four levels
- Foot switch to activate the heating process
- Very compact and handy system (footprint 300 x 300 mm)
- Usage without software



Unpack, setup, solder! It's as simple as that to rework a PCB nowadays. The Erska **HR 200** hybrid rework system contains a 400 W hybrid highpower heating element to desolder and solder SMT components up to 30 x 30 mm.

As an option, the system can operate a powerful 800 W infrared heating plate. This bottom heater guarantees ideal preheating of the assembly to rework.

The operator selects the required power for top and bottom heating with a control knob, each with four levels. A foot switch activates the heating process. The operator's hands are free to remove the desoldered component with appropriate tools.

Depending on the assembly and the preselected power a typical soldering time for components can range from 60 to 180 s (1 -3 min). During working breaks,

the bottom heater switches back to standby level. The integrated PCB holder positions the assembly in optimum working distance to top and bottom heater. Erska recommends an optional cooling fan, a thermocouple sensor and a temperature measuring instrument to complete the workplace. Additional accessories including a Reflow Process Camera to observe the soldering processes round off the equipment.

Technical Data

Station	Rating/Voltage	Heated area	Weight*
HR 200	400 W/230 V respectively 115 V, 50 – 60 Hz	30 x 30 mm	3.7 kg
Heating plate	800 W/230 V respectively 115 V, 50 – 60 Hz	125 x 125 mm	2.5 kg

*without cable

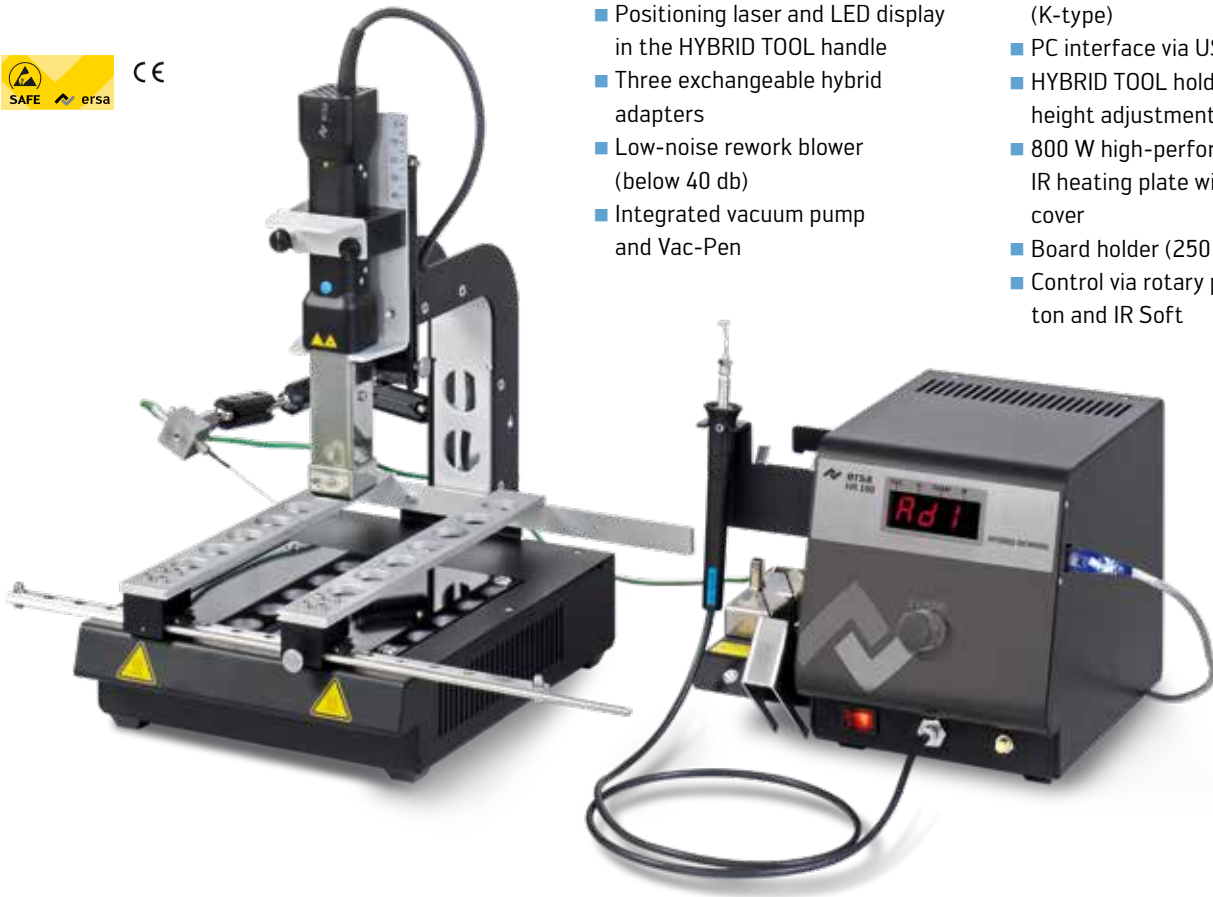
ERSA HR 100 & IRHP 100

Combined handheld and tabletop rework station



Technical highlights:

- HYBRID TOOL with 200 W heating element
- Positioning laser and LED display in the HYBRID TOOL handle
- Three exchangeable hybrid adapters
- Low-noise rework blower (below 40 db)
- Integrated vacuum pump and Vac-Pen
- Temperature recording via AccuTC thermocouple (K-type)
- PC interface via USB port
- HYBRID TOOL holder with height adjustment
- 800 W high-performance IR heating plate with glass cover
- Board holder (250 x 290 mm)
- Control via rotary push button and IR Soft



The **HR 100** uses Ersa's revolutionary and patented hybrid rework technology for safe removal and replacement of small SMDs. Safe, medium wave IR radiation combined with a gentle hot-air stream guarantees optimal energy transfer to the component.

The HYBRID TOOL delivers smooth and homogenous heat to components. Interchangeable hybrid adapters direct up to 200 W of targeted hybrid heat to the component - and adjacent areas are protected. The user-friendly operation allows for even non-experienced operators to handle the HR 100 safely and quickly.

The handle of Ersa's ergonomically designed HYBRID TOOL contains a positioning laser which helps the operator to focus the heat precisely throughout the entire process. Via the USB 2.0 port, the HR 100 can be connected to Ersa's top-of-the-line and well-established IR Soft rework software.

Order information:

Order no.	Description
01RHR100A	HR 100 hybrid rework system, complete, with HYBRID TOOL (31RHR100A-01), Vac-Pen vacuum pipette (0VPO20), hybrid adapters 01RHR100A-14, -15, -16 and adapter changer 01RHR100A-24
11RHR100A0A67	HR 100, 115 V version
01RHR100A-HP	HR 100 hybrid rework system, complete, with HYBRID TOOL (31RHR100A-01), Vac-Pen vacuum pipette (0VPO20), 3 hybrid adapters, adapter changer, HYBRID TOOL holder and IR heating plate with PCB holder
11RHR100AHPA67	HR 100 with heating plate, 115 V version
01RHR-ST050	Hybrid rework tripod, complete

Technical Data

Station	Rating/Voltage	Heated area	Weight*
HR 100	200 W/230 V respectively 115 V, 50 – 60 Hz		
HYBRID TOOL		6 x 6 mm to 20 x 20 mm	300 g
Heating plate	200 W, 800 W/230 V respectively 115 V, 50 – 60 Hz	125 x 125 mm	2.5 kg

*without cable



Component is lifted off the print stencil

DIP&PRINT STATION

For Erska rework systems

Technical highlights:

- Easy solder paste printing on the component
- Component dip-in for solder paste or flux
- Fits for every Erska rework system
- Easy stencil exchange
- Easy cleaning



Flux application in a dip stencil

The user of an Erska rework system can prepare components (application of solder paste or flux) in an easy, reliable and reproducible manner with the Erska **Dip&Print Station**.

Optionally available dip stencils permit – using defined parameters – to

immerse the components into flux or solder paste, building up a defined depot on the contacts to be soldered. This method is suitable for BGAs and for most fine-pitch components. Using a component specific print stencil, solder paste depots can be easily and precisely be added on QFN/MLF pins, for example, and on pins of other SMD components.

In the printing process, the solder paste is applied from below onto the component fixed in the print stencil. The component is then lifted off the stencil with the placement unit and positioned on the board.

A fitting frame fixation is available for every Erska rework system to install the Dip&Print Station's stencil frame on the placement unit.



Dip&Print Station with accessories

Order information:

Order no.	Description
OPR100	Dip&Print Station
OPR100-PL550	Frame fixation for PL 550
OPR100-PL650	Frame fixation for PL 650
OPR100-D001	Dip stencil, 40 x 40 mm/300 µm
OPR100-D002	Dip stencil, 20 x 20 mm/150 µm
OPR100-D003	Dip stencil, 20 x 20 mm/100 µm

Customized and further stencils on request